



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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SMT Inductors

Transponder coils

Size $4.5 \times 3.2 \times 3.2$ mm, 4532 (IEC) / 1812 (EIA)

Series/Type: **B82451A2384D000**

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SMD
Size 4532 (IEC) / 1812 (EIA)
Construction

- Ferrite drum core
- Winding: laser-welded with non-solderable wire
- Flame-retardant molding


Features

- Temperature range up to +125 °C
- Qualified to AEC-Q200
- High sensitivity in Z direction
- High quality factor
- Suitable for lead-free reflow soldering as referenced in JEDEC J-STD 020D
- RoHS-compatible

Applications

- Transponder coil in TPMS (Tire Pressure Monitoring Systems)

Terminals

- Base material CuSn6
- Layer composition Cu, Ag, Sn (lead-free)
- Electro-plated

Marking

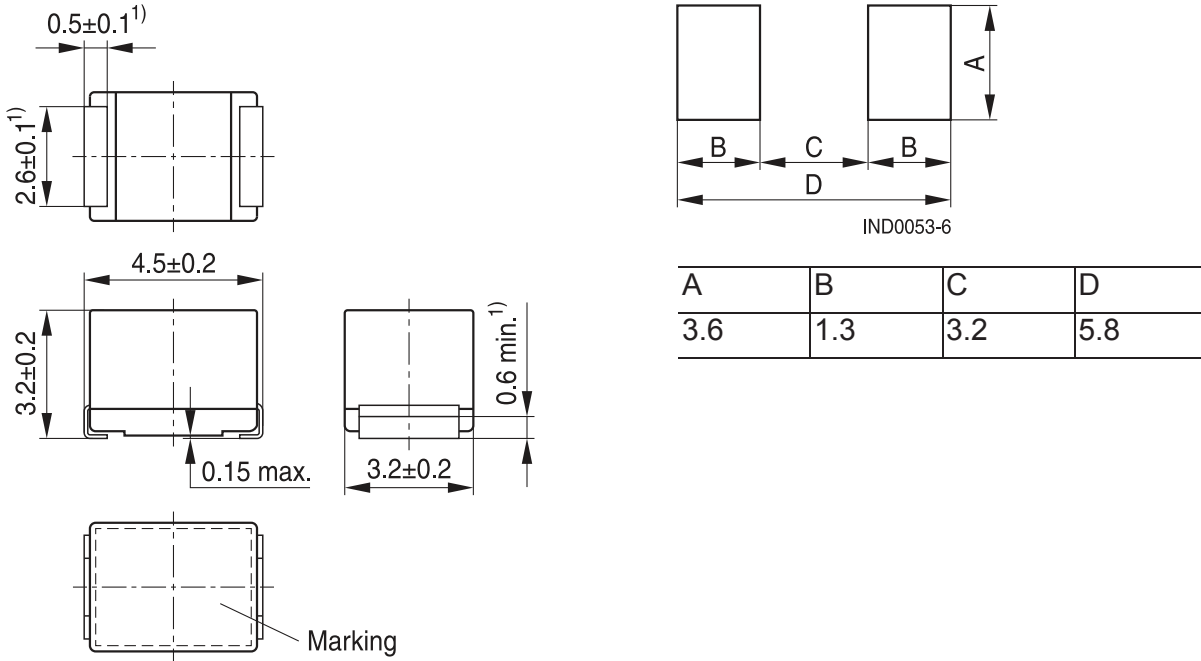
- Marking on component:
Manufacturer, L value (nH, coded without exponent), letter "D", date of manufacture (YWWD)
- Minimum data on reel:
Manufacturer, ordering code, L value, quantity, date of packing

Delivery mode and packing unit

- 12-mm blister tape, wound on 330-mm Ø reel
- Packing unit: 2500 pcs./reel

SMD

Dimensional drawing and layout recommendation



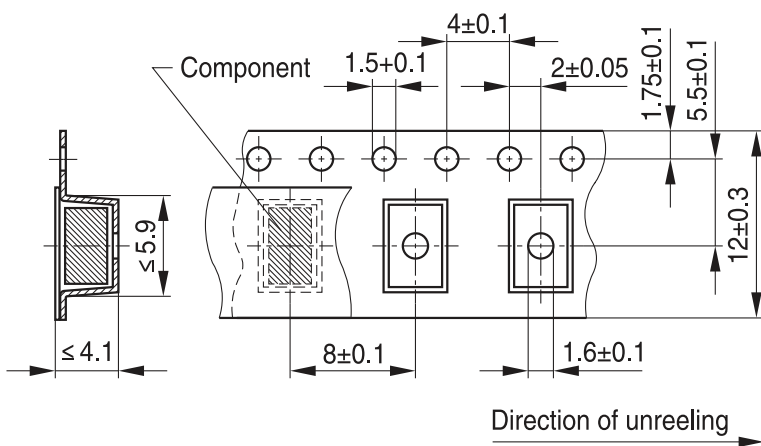
1) Soldering area

IND0083-T-E

Dimensions in mm

Taping and packing

Blister tape

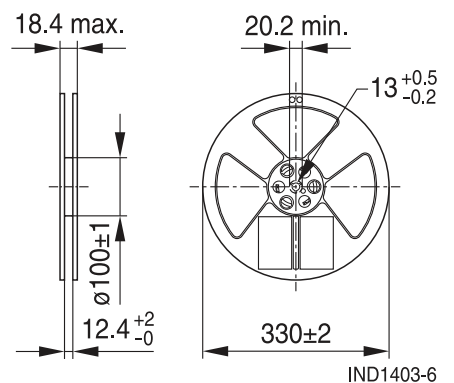


Direction of unreeling

IND0561-L-E

Dimensions in mm

Reel



IND1403-6

SMD
Technical data and measuring conditions

Rated inductance L_R	Measured with impedance analyzer Agilent 4294A at frequency f_L , 0.5 V, +20 °C
Q factor Q_{min}	Measured with impedance analyzer Agilent 4294A at frequency f_Q , +20 °C
Rated temperature T_R	+125 °C
Self-resonance frequency $f_{res,min}$	Measuring with network analyzer Agilent 8753D, +20 °C
DC resistance R_{max}	Measured at +20 °C
Solderability (lead-free)	Sn95.5Ag3.8Cu0.7: +(245 ±5) °C, (5±0.3) s Wetting of soldering area ≥ 90% (based on IEC 60068-2-58)
Resistance to soldering heat	+260 °C, 40 s (as referenced in JEDEC J-STD 020D)
Climatic category	40/125/56 (to IEC 60068-1)
Storage conditions	Mounted: -40 °C ... +125 °C Packaged: -25 °C ... +40 °C, ≤ 75% RH
Weight	Approx. 120 mg

Characteristics and ordering codes

L_R	L tolerance	f_L, f_Q	Q_{min}	S_{typ} $\frac{mV}{\mu T}$	R_{max}	f_{res}	Ordering code
μH		kHz		Ω		MHz	
2380	±5%	125	25	7.6	43	> 1.5	B82451A2384D000

Cautions and warnings

- Please note the recommendations in our Inductors data book (latest edition) and in the data sheets.
 - Particular attention should be paid to the derating curves given there.
 - The soldering conditions should also be observed. Temperatures quoted in relation to wave soldering refer to the pin, not the housing.
- If the components are to be washed varnished it is necessary to check whether the washing varnish agent that is used has a negative effect on the wire insulation, any plastics that are used, or on glued joints. In particular, it is possible for washing varnish agent residues to have a negative effect in the long-term on wire insulation.
Washing processes may damage the product due to the possible static or cyclic mechanical loads (e.g. ultrasonic cleaning). They may cause cracks to develop on the product and its parts, which might lead to reduced reliability or lifetime.
- The following points must be observed if the components are potted in customer applications:
 - Many potting materials shrink as they harden. They therefore exert a pressure on the plastic housing or core. This pressure can have a deleterious effect on electrical properties, and in extreme cases can damage the core or plastic housing mechanically.
 - It is necessary to check whether the potting material used attacks or destroys the wire insulation, plastics or glue.
 - The effect of the potting material can change the high-frequency behaviour of the components.
- Ferrites are sensitive to direct impact. This can cause the core material to flake, or lead to breakage of the core.
- Even for customer-specific products, conclusive validation of the component in the circuit can only be carried out by the customer.

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